



Material Content Data Sheet



Sales Product Name	TLE6214L			Issued		28. August 2013		
MA#	MA001040882							
Package	PG-DSO-12-11			Weight*		406.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.431	2.81	2.81	28106	28106
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		566	
	inorganic material	phosphorus	7723-14-0	0.069	0.02		170	
	non noble metal	copper	7440-50-8	230.106	56.58	56.66	565748	566484
wire	non noble metal	aluminium	7429-90-5	0.416	0.10	0.10	1024	1024
encapsulation	organic material	carbon black	1333-86-4	0.300	0.07		738	
	plastics	epoxy resin	-	13.812	3.40		33959	
	inorganic material	silicondioxide	60676-86-0	136.021	33.44	36.91	334426	369123
leadfinish	non noble metal	tin	7440-31-5	4.235	1.04	1.04	10413	10413
plating	inorganic material	phosphorus	7723-14-0	0.002	0.00		4	
	non noble metal	nickel	7440-02-0	0.630	0.15	0.15	1549	1553
solder	noble metal	silver	7440-22-4	0.237	0.06		582	
	non noble metal	tin	7440-31-5	0.190	0.05		466	
	non noble metal	lead	7439-92-1	9.049	2.22	2.33	22249	23297
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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